



Title: INSULATED BONDING WIRE FOR MICROELECTRONIC PACKAGING

Inventors: Chia et al.

Application No. 09/687,263 / Attorney Docket No. 00-58510

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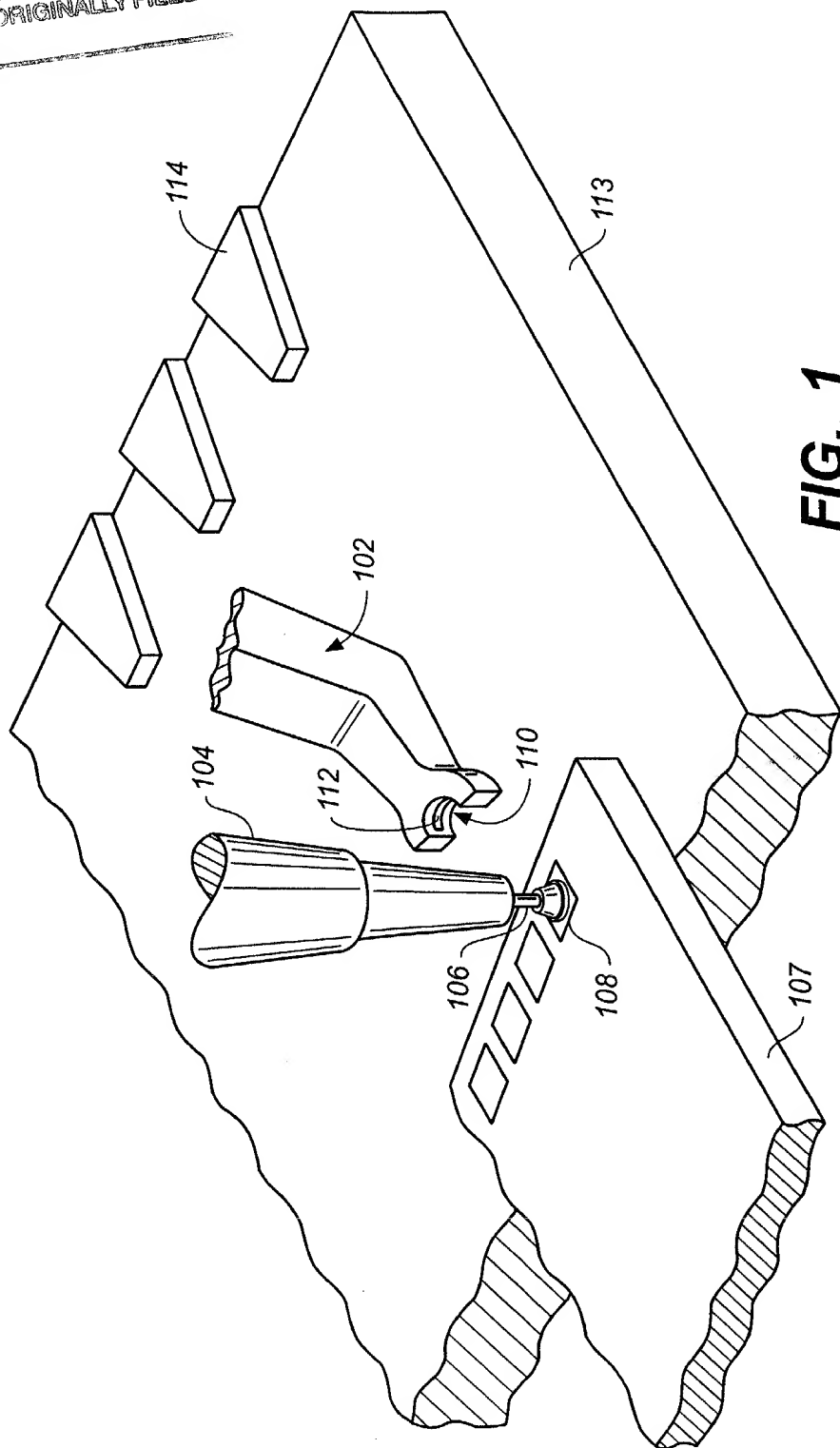


FIG. 1

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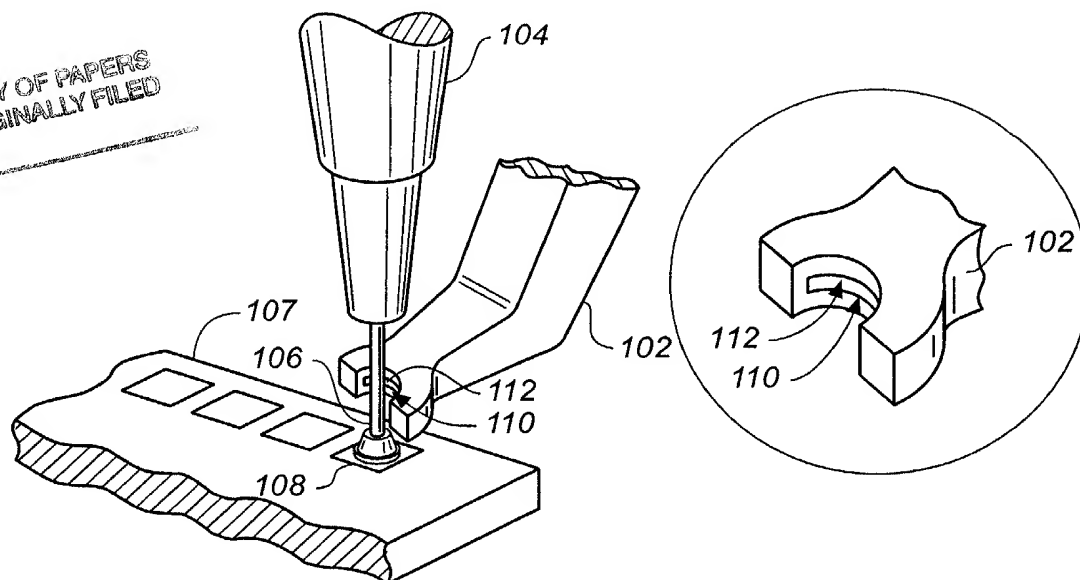
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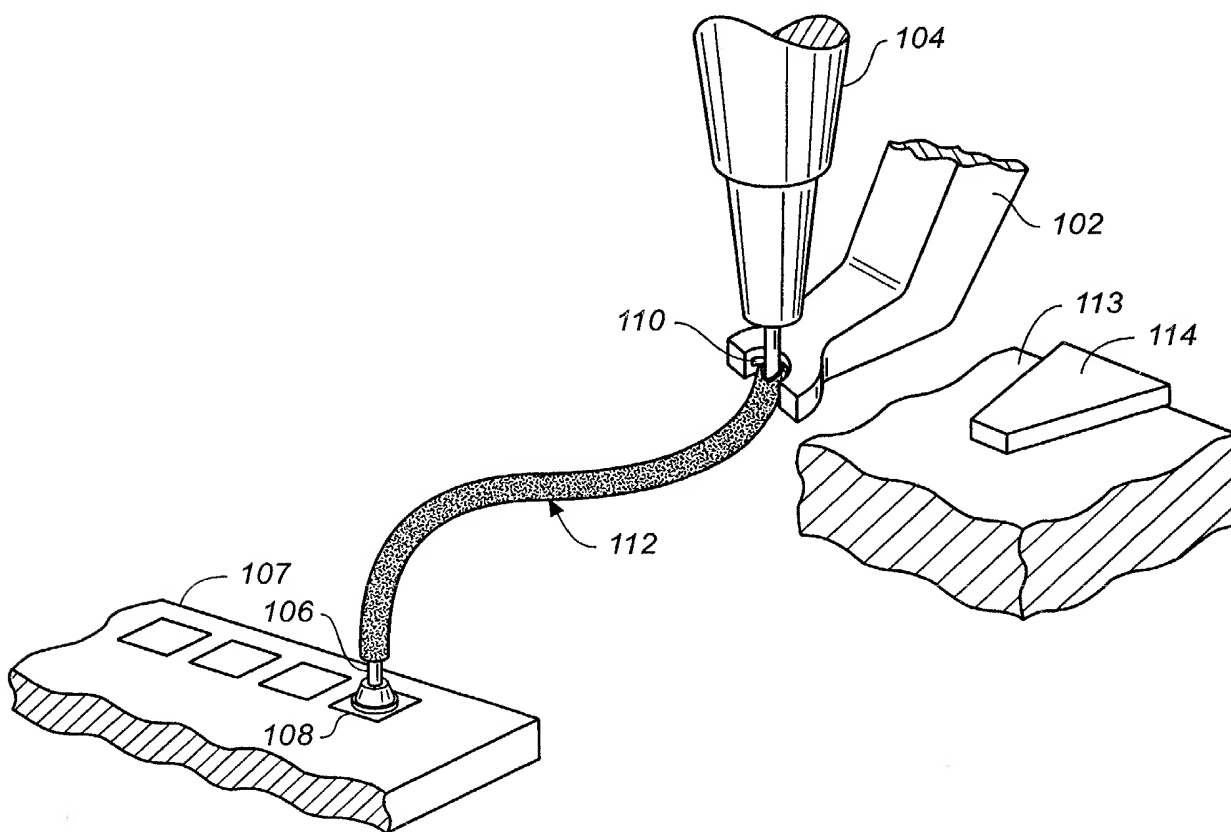
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**FIG.\_2**

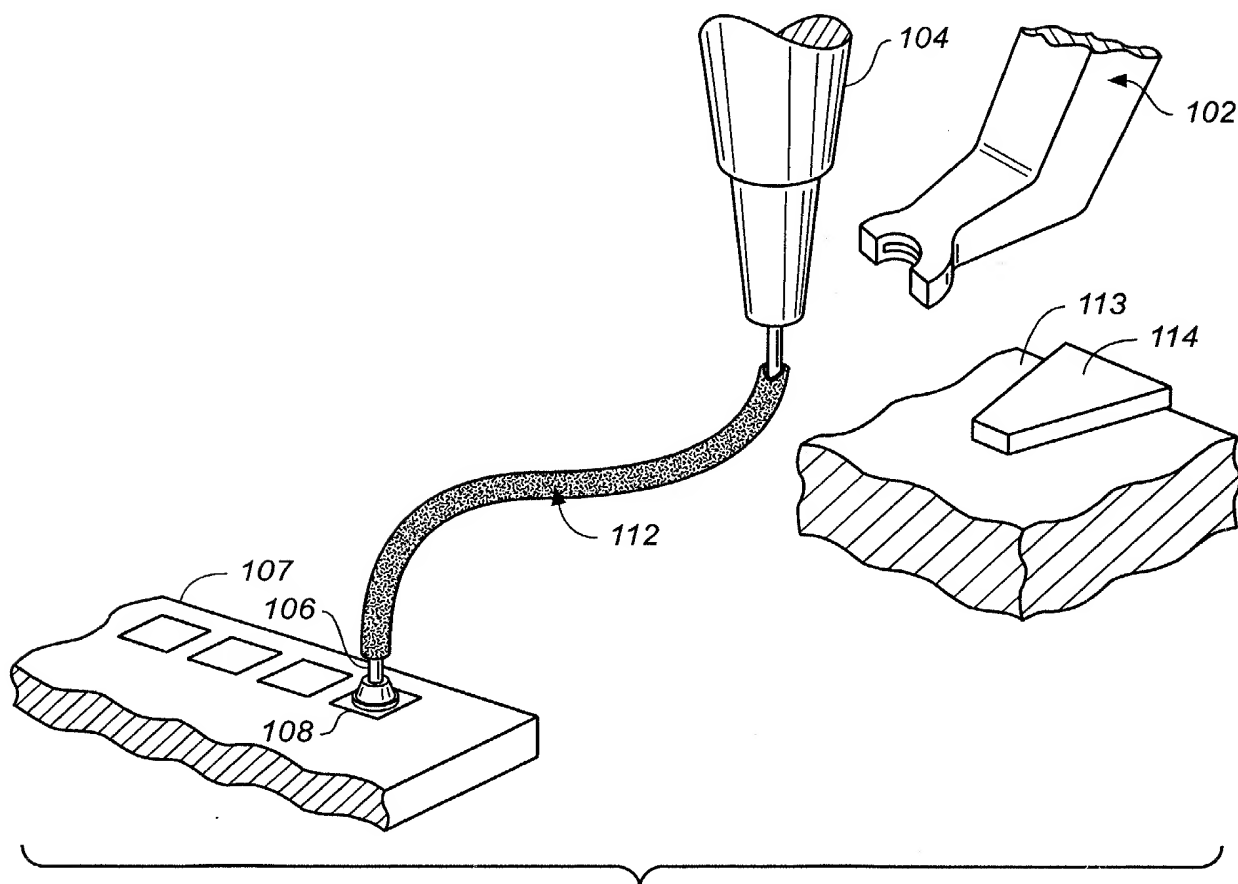


**FIG.\_3**



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**FIG. 4**

